

# Patent Abstracts of Japan

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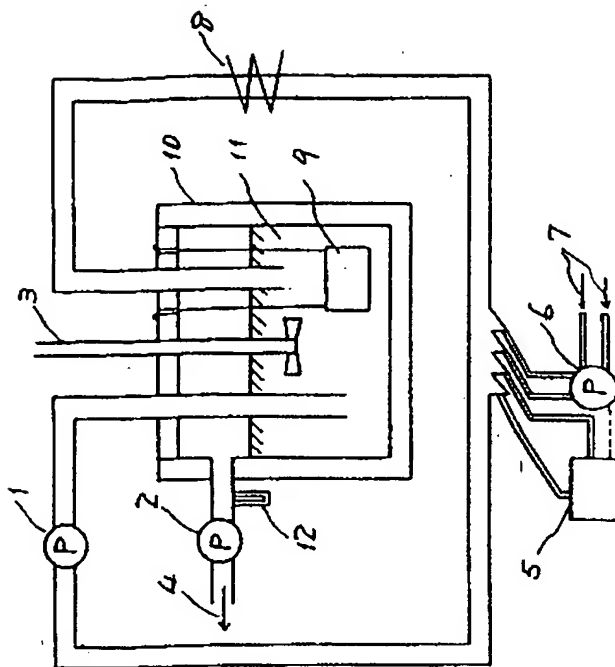
APPLICATION DATE : 27-06-84  
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TITLE : METHOD FOR CARRYING OUT  
ELECTROLESS COPPER PLATING



ABSTRACT : PURPOSE: To improve the mechanical properties of a plated film as well as to increase the rate of plating by carrying out electroless copper plating under reduced pressure.

CONSTITUTION: A body 9 to be plated is immersed in an electroless copper plating soln. 11 in a plating tank 10, and gaseous hydrogen 4 in the plating soln. 11 is exhausted with a vacuum pump 2. In the figure, 12 is a vacuum gauge. By the degassing, the mechanical properties of a copper film deposited by plating are improved, and the film is made free from defects such as blister and pits. An effect produced by raising the temp. of the plating soln. corresponds to that obtd. by reducing the pressure, so the rate of plating can be increased.

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